QuickLogic and GLOBALFOUNDRIES Collaborate to Deliver Next-Generation Sensor Hub for Smartphones and Wearables

September 8, 2014

ArcticLink® 3 S2 silicon platform to use 65nm process technologies

Sunnyvale and Santa Clara, Calif., September 8, 2014 – QuickLogic Corporation (NASDAQ: QUIK), the innovator of ultra-low power programmable Customer Specific Standard Products (CSSPs), and GLOBALFOUNDRIES, a leading provider of advanced semiconductor manufacturing technology, today announced that QuickLogic's next-generation ArcticLink 3 S2 Ultra-low Power Sensor Hub is sampling on GF's low-power 65 nanometer (nm) process technology.

The ArcticLink 3 S2 Sensor Hub is an ultra-low power, context-aware sensor hub optimized for smartphone and wearable devices. Building on QuickLogic's ArcticLink 3 S1, the S2 offers OEMs four times the computational capability, four times the sensor algorithm memory, and eight times the sensor data memory in a pin-identical footprint.

The ArcticLink® 3 S2 leverages GF's 65nm LPe (low-power enhanced) technology, which uses innovative leakage reduction techniques to significantly improve power utilization and extend battery life, making it especially well-suited for battery-operated and cost-sensitive mobile applications. The S2 Sensor Hub is expected to be production-certified in Q4 2014.

"The fast-growing market for sensor hubs in smartphones and wearables presents a wide array of new applications that match perfectly with our ArcticLink 3 S2 sensor hub solution," said Brian Faith, VP of worldwide sales and marketing at QuickLogic. "This new collaboration with GF as the manufacturer for the S2 platform will help us meet our demanding time-to-market requirements with a technology that delivers the right balance of performance, power consumption, and cost."

"As the industry continues its seismic shift from PC to mobility, a whole new set of applications and devices are driving the need for differentiated silicon solutions," said Gregg Bartlett, senior vice president of product management at GF. "Innovative designers like QuickLogic need a collaborative foundry to help them bring their creative ideas to market, and we are pleased to partner with them to deliver their next-generation sensor hub on our 65nm technology."

About QuickLogic

QuickLogic Corporation is the inventor and pioneer of innovative, customizable semiconductor solutions for mobile and portable electronics OEMs and ODMs. These silicon platforms plus software solutions are called Customer Specific Standard Products (CSSPs). CSSPs enable our customers to bring their products to market more quickly and remain in the market longer, with the low power, cost and size demanded by the mobile and portable electronics market. For more information about QuickLogic and CSSPs, visit www.quicklogic.com

About GF

GF is the world's first full-service semiconductor foundry with a truly global footprint. Launched in March 2009, the company has quickly achieved scale as the second largest foundry in the world, providing a unique combination of advanced technology and manufacturing to more than 160 customers. With operations in Singapore, Germany and the United States, GF is the only foundry that offers the flexibility and security of manufacturing centers spanning three continents. The company's three 300mm fabs and five 200mm fabs provide the full range of process technologies from mainstream to the leading edge. This global manufacturing footprint is supported by major facilities for research, development and design enablement located near hubs of semiconductor activity in the United States, Europe and Asia. GF is owned by Mubadala Development Company. For more information, visit http://www.globalfoundries.com.

Contacts:

Jason Gorss
GLOBALFOUNDRIES
(518) 305-9022
jason.gorss@globalfoundries.com

Andrea Vedanayagam
Veda Communications
(408) 656-4494
pr@quicklogic.com